

# MVR5510AMBANES – NXP Standard

## Configuration report for ASILB OTP program ID: AN rev C

Rev. 1.0 - Feb 9 2022

Report

### 1 General description

The VR5510 is an automotive multi-output power management integrated circuit, with focus on Gateway, V2X and Infotainment applications. It includes multiple high efficiency switch mode and linear voltage regulators. It offers external frequency synchronization input and output, for optimized system EMC performance.

The VR5510 includes enhanced safety features, with fail-safe output, becoming a full part of a safety-oriented system partitioning, covering both ASILB and ASILD safety integrity level. It is developed in compliance with ISO 26262 standard.

### 2 Features and benefits

- 60V DC maximum input voltage
- Configurable VPRE synchronous buck controller with external MOSFETs.
- Configurable Single/dual-Phase Low voltage buck converters with DVS capability
- Configurable Low voltage integrated synchronous BUCK3 converter
- BOOST converter with integrated low side switch
- 3x linear voltage regulators with configurable Output Voltage
- High voltage linear regulator (HVLDO) with LDO and Switch mode operation
- EMC optimization with frequency tuning, clock synchronization, frequency spread spectrum and slew rate control
- Low power standby mode (40uA quiescent Current)
- 2x input pins for wake-up detection and battery voltage sense
- Device control via I2C interface with CRC (up to 3.4 MHz)
- Selectable OTP Default configuration

### 3 Applications

- Automotive Infotainment
- High - End Industrial

### 4 Ordering information

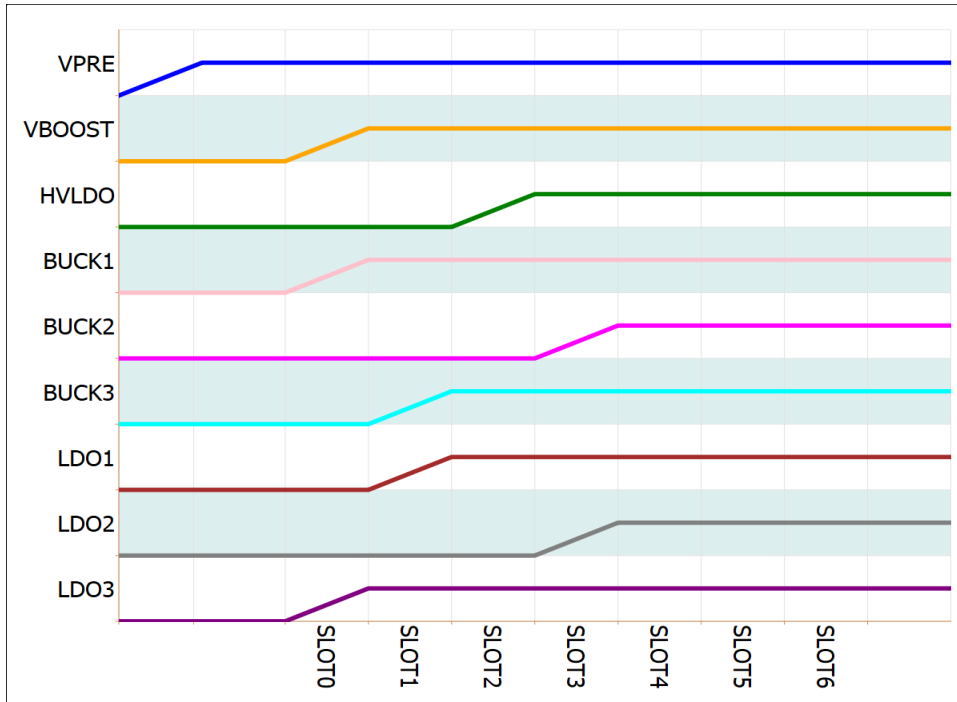
Table 1. Ordering information

Type number <sup>[1]</sup>	Package		
	Name	Description	Version
MVR5510AMBANES	QFN56 EP	QFN56 plastic thermally enhanced very thin quad flat non-leaded package. Wettable flanks; 56 terminals; 0.5mm pitch, 8mmx8mmx0.85mm body	SOT684-21

[1] To order parts in tape and reel, add the R2 suffix to the part number.

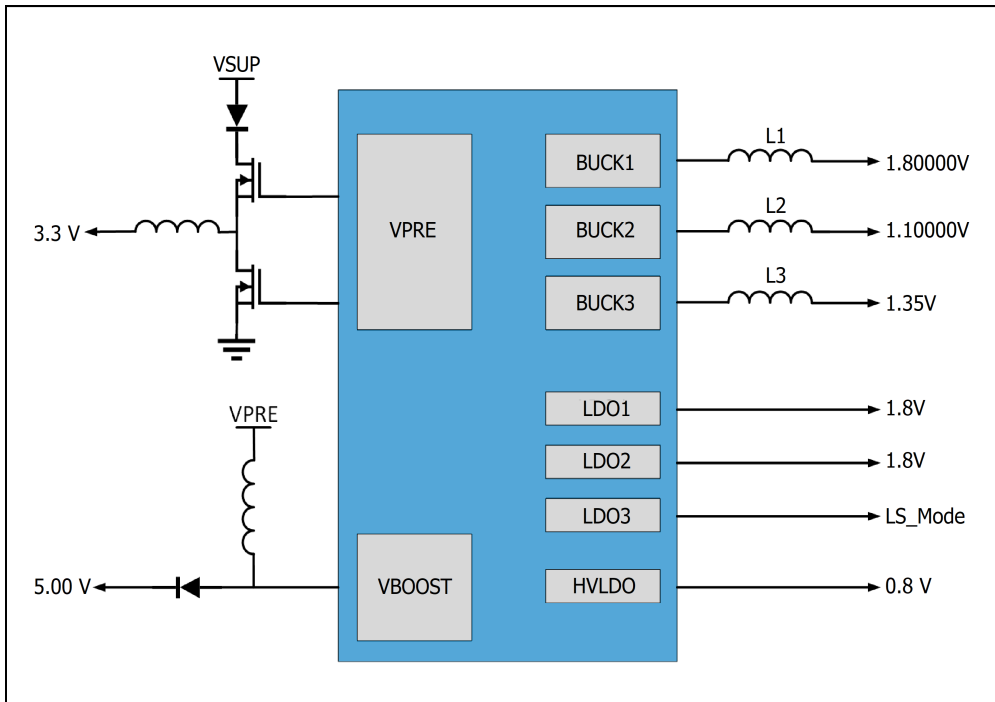


## 5 Power-up sequence summary



The signals depicted above are enable signals for each regulator. They don't represent the actual ramp voltage

## 6 Hardware configuration diagram



## 7 System configuration

See VR5510 datasheet for parametric details. The OTP configuration summary for AN sequence ID is provided in Tables below.

**Table 2. Device OTP configuration**

Functional block	Feature	OTP selection
Device Configuration	Main I2C Address	0x20
	VSUP UV threshold	4.9V
	Auto Re-try Enable	Enabled (default)
	Auto Re-try Timeout	4 s (default)
	Number of Retries	Infinite Retry (default)
	PLL Enable	Disabled (default)
	Clock 1 Divider	2.22 MHz (default)
	Clock 2 Divider	455 KHz (default)
	Thermal Warning TH	105 $\mu$ C (default)
	Deep Sleep Enable	DSM Disabled (default)
IO Configuration	PWRON2 Control	Not Required
	AMUX/FOUT Select	AMUX Enabled (default)
	PSYNC Enable	PSYNC Disabled (default)
	PSYNC Mode	Sync VR5510 + LV PMIC
	PSYNC Power Down Ctrl	Ignore for PwrDown
	Standby Transition Timer	Enabled (default)
	Standby Discharge TH	75 mV (default)
	Standby Polarity	Active Low (default)
	Standby PGOOD Enable	Enabled (default)
	PSYNC PGOOD Ext	Enabled

## Configuration report for ASILB OTP program ID: AN rev C

	Ext Standby Discharge	Enabled
	Standby PGOOD Delay	400us for HVLDO = 3.3V
	VDDIO Supply Seletion	LDO3 (default)
	Multiphase Configuration	Single Phase

**Table 3. Voltage Regulators Configuration**

Functional block	Feature	OTP selection
VPRE Configuration	VPRE Voltage	3.3 V (default)
	Slope Compensation	41.4mv/us
	VPRE Standby Output Ctrl	Set by VPREV_STBY (I2C)
	ILIM sense Voltage	120 mV
	VPRE HighSide pull down Slew Rate Ctrl	PD/520mA (455Khz default value)
	VPRE HighSide pull up Slew Rate Ctrl	PU/520mA (455Khz default value)
	VPRE LowSide Slew Rate Ctrl	PU/PD/900mA (default value)
	Soft Start Ramp	2 mV/us (default)
	VPRE Off Time	80 ns
	TON in PFM	550 ns (default value)
	TON Min	45 ns
	Turn OFF Delay	250 us
VBOOST Configuration	VBOOST Voltage	5.00 V (default)
	Slope Compensation	67 mV/µs (default)
	Minimum TON	60 ns (default)
	Current Limit	2.25 A (default)
	Low Side Slew Rate Ctrl	500 V/us (default)
	Input Path to BOS	Enabled (default)

## Configuration report for ASILB OTP program ID: AN rev C

	Compensation Capacitor	125 pF (default)
	Compensation Resistor	500 kΩ (default)

**Table 4. BUCK Regulators**

Functional block	Feature	OTP selection
BUCK1 - Single Phase	Output Voltage	1.80000V
	Current Limit	3.6 A
	Output Inductor	1uH(default)
	TransConduct	65 u mho
	DVS Ramp of BUCK1 and BUCK2	7.8mV/us (power up) / 5.2mV/us (power down)
BUCK2 - Single Phase	Output Voltage	1.10000V
	Current Limit	3.6 A
	Output Inductor	1uH(default)
	TransConduct	65 u mho
BUCK3	Output Voltage	1.35V
	Current Limit	3.6 A
	Output Inductor	1uH(default)
	Ramp	3.47mV/us (power up/down)
	TransConduct BUCK3	65 u mho
	R Comp	56 KΩ

**Table 5. LDO Regulators**

Functional block	Feature	OTP selection
LDO1 Regulator	Output Voltage	1.8V
	Current Limit	400 mA (default)

## Configuration report for ASILB OTP program ID: AN rev C

LDO2 Regulator	Output Voltage	1.8V
	LDO Mode	LDO Mode (default)
LDO3 Regulator	Output Voltage	LS_Mode
	LDO Mode	Load Switch (default)

**Table 6. HVLDO Regulator**

Functional block	Feature	OTP selection
HVLDO Regulator	HVLDO Voltage	0.8 V (default)
	Sequence Control	Follows HVLDO_OTP slot
	Transition Mode	Switch in Normal / LDO in Standby (default)

**Table 7. Voltage Sequence and Timing Configuration**

Regulator	Sequence	Enabled	Phase Delay	Clock	TSD Event
VPRE	Auto-enabled	Enabled	No delay	CLK2	
VBOOST	Slot 0	Enabled	No delay	CLK1	Shutdown + DFS
BUCK1	Slot 0	Enabled	1 clock delay	CLK1	Shutdown + DFS
BUCK2	Slot 3	Enabled	2 clock delay	CLK1	Shutdown + DFS
BUCK3	Slot 1	Enabled	3 clock delay	CLK1	Shutdown + DFS
LDO1	Slot 1	Enabled			Shutdown + DFS
LDO2	Slot 3	Enabled			Shutdown + DFS
LDO3	Slot 0	Enabled			Shutdown + DFS
HVLDO	Slot 2	Enabled			Shutdown + DFS
SLOT Width	250 us				

**Table 8. Safety State Machine Configuration**

Functional block	Feature	OTP selection
Safety Configuration	FailSafe I2C Address	0x21

## Configuration report for ASILB OTP program ID: AN rev C

8sec Timer to DFS	Timer Enabled
ABIST1 to RSTB delay	No Delay (default)
VCOREMON SVS Clamp Limit	No SVS
VCOREMON SVS Offset Type	Negative offset (default)
PGOOD assert with RSTB	PGOOD Asserts with RSTB Fault (default)
HVLDO Mode Select	Switch Mode (default)
WDI Polarity	Falling Edge
WDI on FCCU1	WDI Disabled (default)
STANDBY Mode	STANDBY Enabled (default)
STANDBY Polarity	Active Low in standby mode (default)
STANDBY Request Path	I2C + STBY Pin Transition (default)
STANDBY Window	STBY Window Enabled (default)
WD Init Timeout	1024ms
Fault Recovery Mode	Disabled
WD Selection	Simple WD
WD Monitoring	WD Enabled (default)
FCCU Monitoring	FCCU Enabled (default)
LBIST Enable	LBIST Disabled

**Table 9. Voltage Monitoring**

	VMONEN	Voltage	UV_TH	OV_TH	UV Dbnc	OV Dbnc	PGOOD Ctrl	ABIST Ctrl
<b>VCOREMON</b>	Enabled	1.80000V	95.5%	104.5%	25 us	25 us	PGOOD Assigned	ABIST performed
<b>VDDIOMON</b>	Enabled	3.3 V	95%	105%	25 us	25 us	PGOOD Assigned	ABIST performed

## Configuration report for ASILB OTP program ID: AN rev C

<b>HVLDOMON</b>	Disabled	0.8 V	93%	107%	25 us	25 us	Not Assigned	No ABIST at PWRUP
<b>VMON1</b>	Enabled	0.8 V	95.5%	106%	25 us	25 us	PGOOD Assigned	ABIST performed
<b>VMON2</b>	Enabled	0.8 V	97.5%	104.5%	25 us	25 us	PGOOD Assigned	ABIST performed
<b>VMON3</b>	Enabled	0.8 V	95.5%	106%	25 us	25 us	PGOOD Assigned	ABIST performed
<b>VMON4</b>	Enabled	0.8 V	95%	105%	25 us	25 us	PGOOD Assigned	ABIST performed



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### Contents

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1 General description .....	1
2 Features and benefits .....	1
3 Applications .....	1
4 Ordering information .....	1
5 Power up sequence summary .....	2
6 Hardware configuration diagram .....	2
7 OTP configuration .....	3
8 Legal information .....	9

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